Packaging Contents

December 1998

Application Notes

AN 71 Guidelines for Handling J-Lead & QFP Devices

AN 80 Selecting Sockets for Altera Devices

AN 81 Reflow Soldering Guidelines for Surface-Mount Devices

Brochures

Corporate Brochure

Packaging Solutions Brochure

Data Sheets

Altera Device Package Information Data Sheet

Configuration Elements Data Sheet

General Information

Introduction (to the Altera ***1998 Data Book***)

Ordering Information

White Papers

Using Altera's 1.00-mm FineLine BGA Packages White Paper